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PATENT  
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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Gurtej Singh Sandhu et al. Examiner: Jeff Vockrodt  
Serial No.: 09/940,917 Group Art Unit: 2822  
Filed: August 28, 2001 Docket: 303.676US2  
Title: CHEMICAL VAPOR DEPOSITION OF TITANIUM

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

Commissioner for Patents  
Washington, D.C. 20231

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OCT 25 2002  
TECHNOLOGY CENTER 2800

Applicant has reviewed the Office Action mailed on July 18, 2002. Please amend the above-identified patent application as follows.

**IN THE CLAIMS**

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 44, 60, 64, 68, 72, 77, 81, and 83. The specific amendments to individual claims are detailed in the following marked up set of claims.

44. (Amended) An integrated circuit comprising:  
a layer of a titanium alloy covering the walls and bottom of a contact hole, wherein the titanium alloy comprises titanium and an element selected from the group consisting of zinc, cadmium, mercury, aluminum, gallium, indium, tin, silicon, germanium, lead, arsenic and antimony; and  
a titanium silicide contact coupled to the layer.
60. (Amended) An integrated circuit comprising:  
a semiconductor substrate;  
an electronic device coupled to the semiconductor substrate, the electronic device having an active region;  
an insulating layer over the active region;  
an alloy layer of a titanium alloy covering the walls and bottom of a contact [within a contact] opening in the insulating layer, the contact opening being at least partially